

## CLAIM AMENDMENTS:

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Claim 1 (Currently Amended): A bonding pad structure comprising:

a first pad for bonding; and

at least one second pad <sup>for testing</sup> for probing, coupled with the first pad, wherein both of

the first pad and the second pad are formed on an IC (Integrated Circuit).

Claim 2 (Original): The bonding pad structure according to claim 1, wherein the first pad is coupled with the second pad by a connecting wire.

Claim 3 (Currently Amended): The bonding pad structure according to claim 1, wherein the first pad is one of a plurality of first pads arranged according to a first pad layout on the IC, the second pad is one of a plurality of second pads arranged according to a second pad layout on the IC, and the arrangement of the corresponding second pad layout depends on an the arrangement of testing probe in probes for IC probing.

Claim 4 (Currently Amended): The bonding pad structure according to claim 3, wherein the first pad layout and the second pad layout are arranged in linear arrangements.

Claim 5 (Currently Amended): The bonding pad structure according to claim 3, wherein the first pad layout and the second pad layout are arranged in staggered arrangements.

Claim 6 (Currently Amended): The bonding pad structure according to claim 3, wherein the first pad layout is ~~arranged in a~~ staggered arrangement and the second pad layout is ~~a arranged in~~ linear arrangement.

Claim 7 (Original): The bonding pad structure according to claim 1, wherein the first pad comprises a bump ball.

Claim 8 (Currently Amended): The bonding pad structure according to claim 1, wherein the bonding pad structure is applied to a flip chip.

Claim 9 (New): A bonding pad structure comprising:

a first pad for bonding; and

at least one second pad for probing, coupled with the first pad, wherein both of the first pad and the second pad are formed on a PCB (printed circuit board).

Claim 10 (New): The bonding pad structure according to claim 9, wherein the first pad is coupled with the second pad by a connecting wire.

Claim 11 (New): The bonding pad structure according to claim 9, wherein the first pad is one of a plurality of first pads arranged according to a first pad layout on the PCB, the second pad is one of a plurality of second pads arranged according to a second pad layout on the PCB, and the second pad layout depends on an arrangement of testing probes for PCB probing.

Claim 12 (New): The bonding pad structure according to claim 11, wherein the first pad layout and the second pad layout are linear arrangements.

Claim 13 (New): The bonding pad structure according to claim 11, wherein the first pad layout and the second pad layout are staggered arrangements.

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*cont* - Claim 14 (New): The bonding pad structure according to claim 11, wherein the first pad layout is a staggered arrangement and the second pad layout is a linear arrangement.

Claim 15 (New): The bonding pad structure according to claim 9, wherein the first pad comprises a bump ball.

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